

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>SHIN-PUU JENG</td> <td>12/26/2013</td> </tr> <tr> <td>WEN-CHIH CHIOU</td> <td>12/26/2013</td> </tr> <tr> <td>KU-FENG YANG</td> <td>12/26/2013</td> </tr> </tbody> </table>		Name	Execution Date	SHIN-PUU JENG	12/26/2013	WEN-CHIH CHIOU	12/26/2013	KU-FENG YANG	12/26/2013
Name	Execution Date								
SHIN-PUU JENG	12/26/2013								
WEN-CHIH CHIOU	12/26/2013								
KU-FENG YANG	12/26/2013								
RECEIVING PARTY DATA									
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. (TSMC)								
Street Address:	NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK								
City:	HSIN-CHU								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14144775</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14144775				
Property Type	Number								
Application Number:	14144775								
CORRESPONDENCE DATA									
Fax Number:	(972)732-9218								
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ATTORNEY DOCKET NUMBER:	TSM13-1186CP1								
NAME OF SUBMITTER:	CINDY C. STOUTEN								
Signature:	/Cindy C. Stouten/								
Date:	12/31/2013								
Total Attachments: 1 source=TSM13-1186CP1-Assignment#page1.tif									

CH \$40.00 14144775

ATTORNEY DOCKET NO. TSM13-1186CP1
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**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and




WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77, Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	TSV Formation			
SIGNATURE OF INVENTOR AND NAME	 Shin-Puu Jeng	 Wen-Chih Chiou	 Ku-Feng Yang	
DATE	2013.12.26	2013.12.26	2013.12.26	
RESIDENCE	Hsin-Chu, Taiwan	Zhunan Township, Taiwan	Dali City, Taiwan	